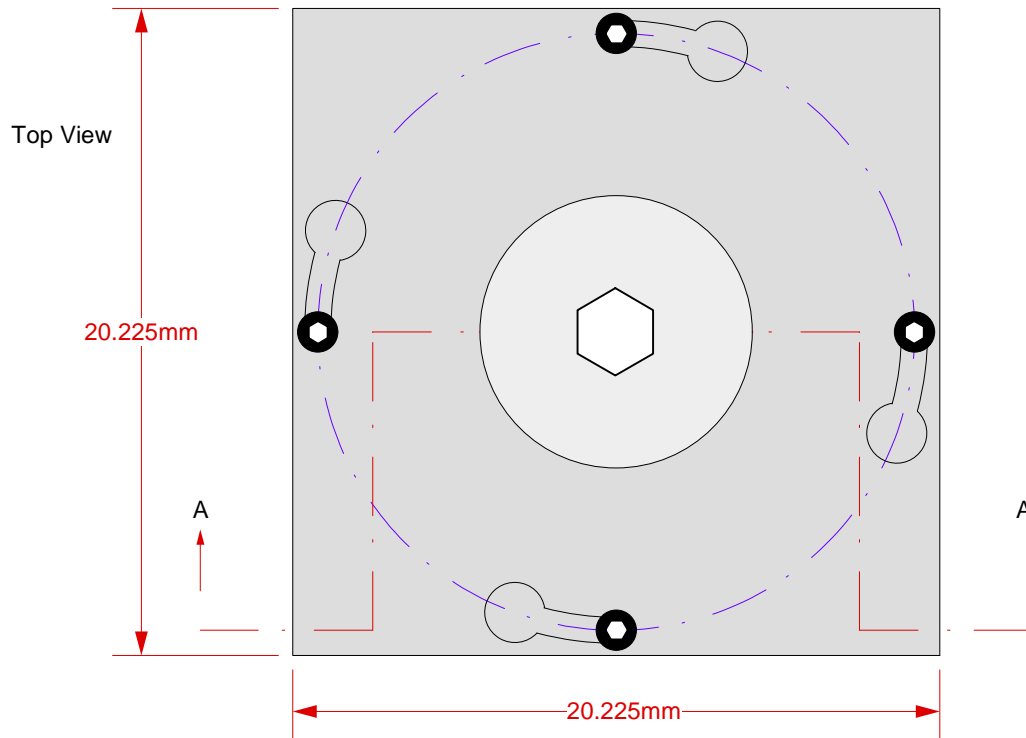
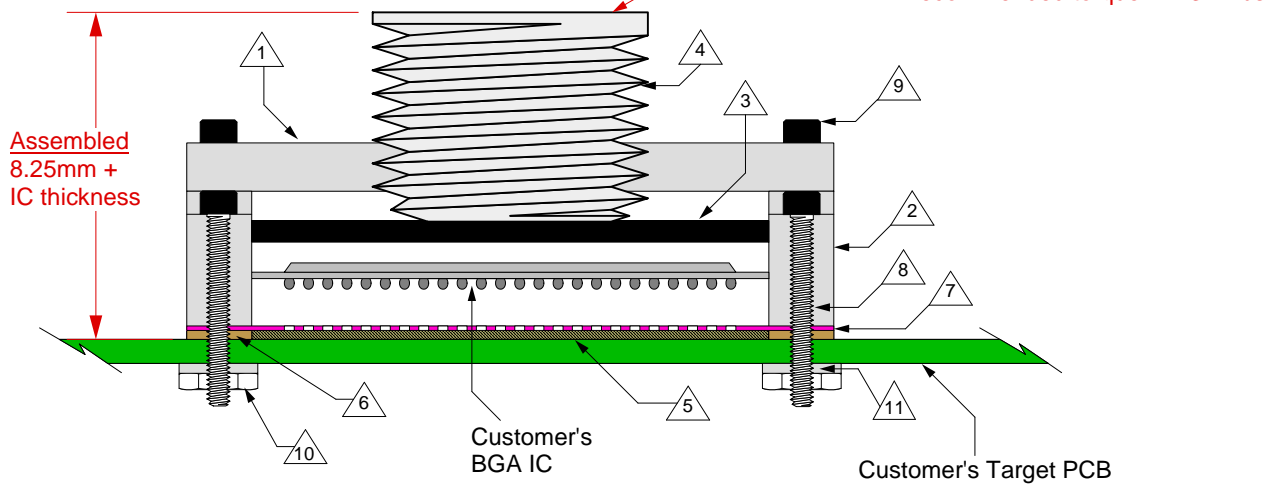


# GHz BGA Socket - Direct mount, solderless



Side View  
(Section AA)



## Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

- 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- 6 Elastomer Guide: ultem 1000. Thickness = 0.725mm.
- 7 Ball Guide: Kapton polyimide.
- 8 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- 10 Socket base nut: 18-8 Stainless steel, 0-80 fine thread.
- 11 Nylon washer: 1.73mm ID; 4.78mm OD 0.64mm thickness.

## SG-BGA-6087 Drawing

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 Tele: (952) 229-8200  
 www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: B

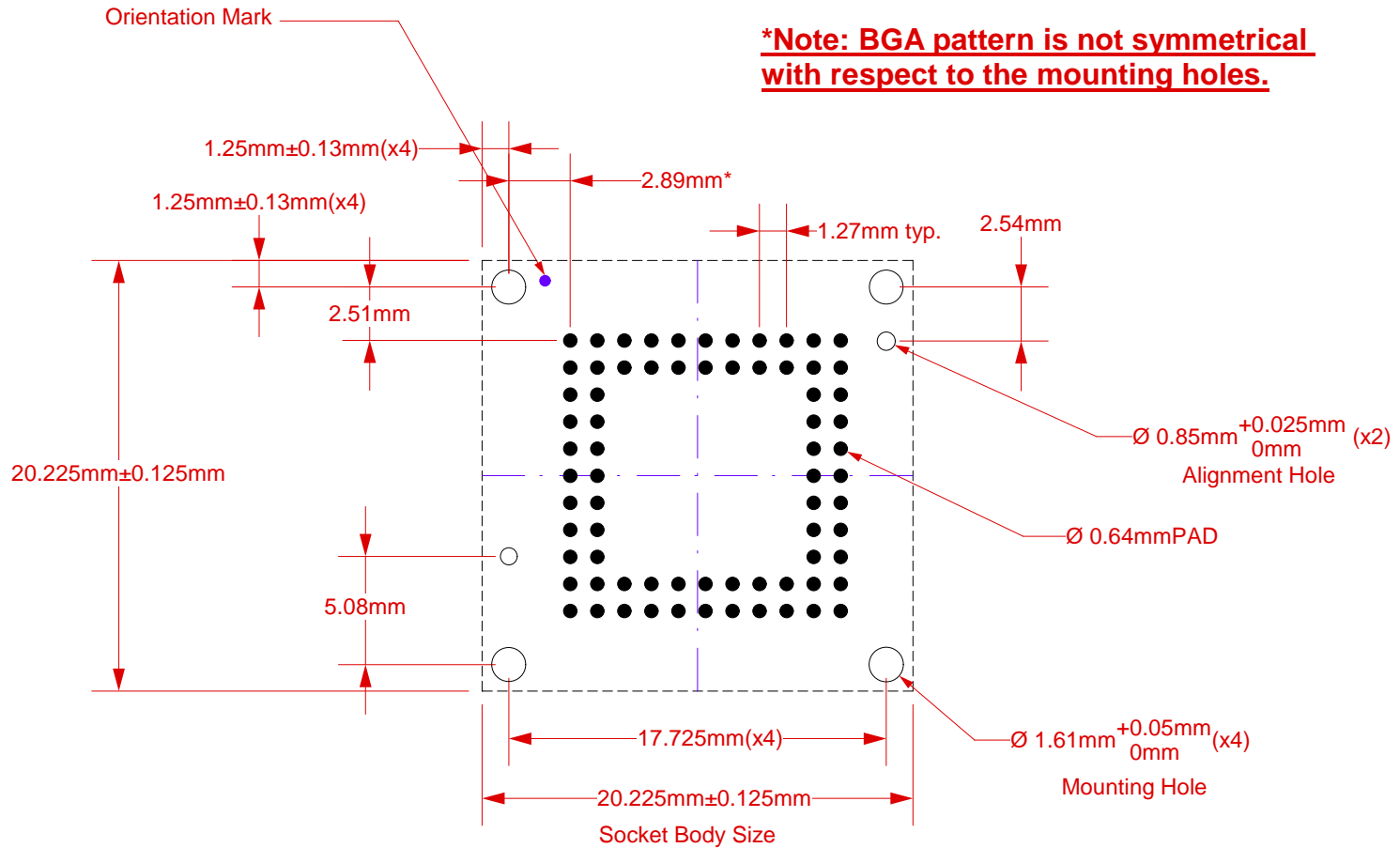
Drawing: H. Hansen

Date: 9/17/03

File: SG-BGA-6087 Dwg.mcd

Modified: 7/2/09, AE

All tolerances:  $\pm 0.125$ mm (unless stated otherwise). Materials and specifications are subject to change without notice.



**Target PCB Recommendations**


Total thickness: 1.6mm min.

Plating: Gold or Solder finish

PCB Pad height: Same or higher than solder mask

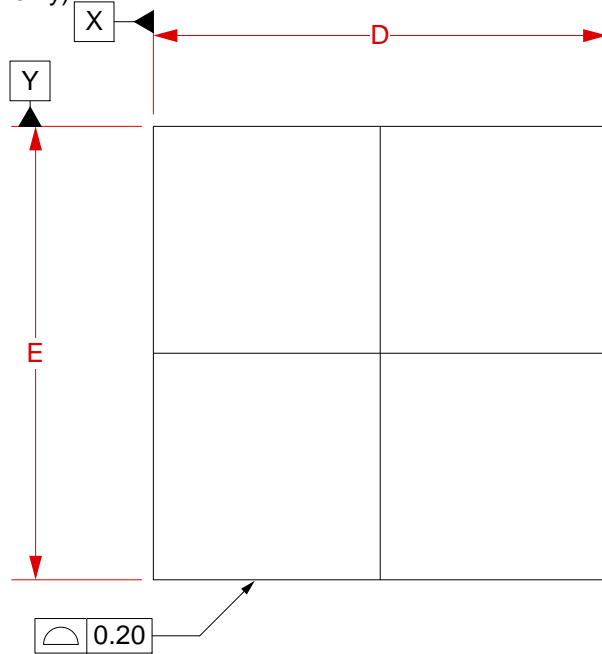
NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

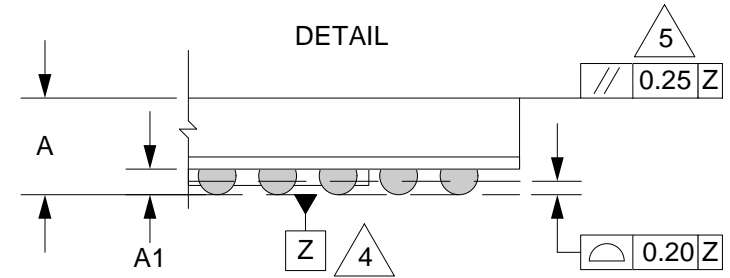
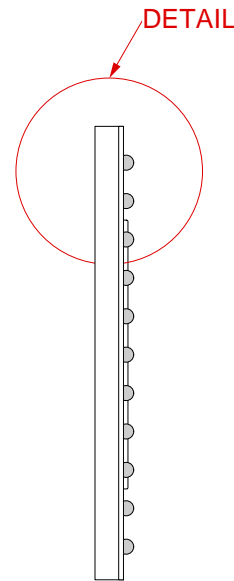
 <p>© 2009 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	<p><b>SG-BGA-6087 Drawing</b></p>	<p>Status: Released</p>	<p>Scale: 3:1</p>	<p>Rev: B</p>
	<p>Drawing: H. Hansen</p>	<p>Date: 9/17/03</p>		<p>Modified: 7/2/09, AE</p>

Top View  
(reference only)

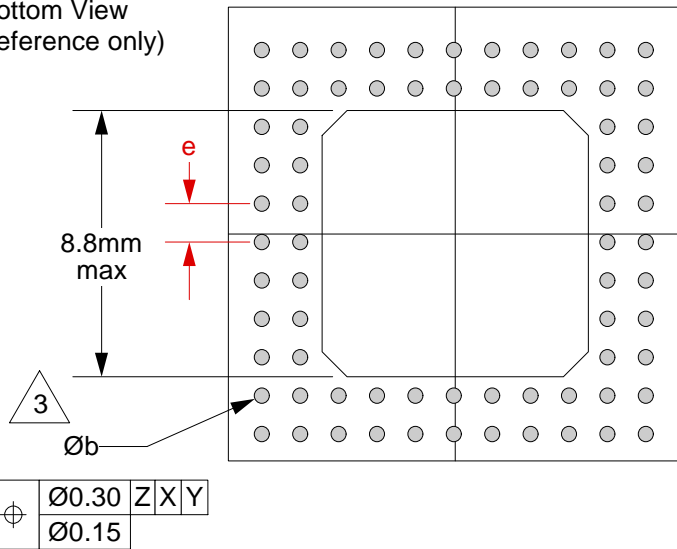
Compatible BGA Spec



Side View  
(reference only)




Bottom View  
(reference only)



1. Dimensions are in millimeters.
  2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		3.50
A1	0.35	
b	0.6	0.735
D	15.00 BSC	
E	15.00 BSC	
e	1.27 BSC	

Array 11x11

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	<p>Drawing: H. Hansen</p>	<p>Date: 9/17/03</p>		
	<p>File: SG-BGA-6087 Dwg.mcd</p>	<p>Modified: 7/2/09, AE</p>		